



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Xi, et al.
Serial No.: 10/052,681
Confirmation No.: 4083
Filed: January 17, 2002
For: Reliability Barrier
Integration for Cu
Application

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

§ Group Art Unit: 2814

§ Examiner: Ginette Peralta

CERTIFICATE OF MAILING 37 CFR 1.8	
I hereby certify that this correspondence is being deposited on <u>9/1/03</u> , 2003 with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.	
Date	<u>Kinu R. Saha</u> Signature

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

The Applicants, and the Attorney who signs below on the basis of the information supplied by the inventor and the information in his file, submit herewith patents, publications, or other information of which they are aware, which may be material to the examination of this application and in respect of which there may be a duty to disclose in accordance with 37 CFR § 1.56.

While the information submitted in this Supplemental Information Disclosure Statement may be material pursuant to 37 CFR § 1.56, it is not intended to constitute an admission that any patent, publication, or other information referred to therein is prior art for this invention unless specifically designated as such.

In accordance with 37 CFR § 1.97, this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or that no other possibly material information as defined under 37 CFR § 1.56(a) exists.

The patents and/or publications submitted herewith are set forth on the attached Form PTO-1449.

09/24/2003 SSESHE1 00000140 200782 10052681

01 FC:1806 180.00 DA

The Commissioner is hereby authorized to charge the sum of \$180.00 due under 37 CFR § 1.17(p) pursuant to § 1.97, and any other fee necessary to make this submission timely, to the Deposit Account No.: 20-0782/AMAT/1931.P1/KMT.

Respectfully submitted,



Keith M. Tackett
Keith M. Tackett
Registration No. 32,008
MOSER, PATTERSON & SHERIDAN, L.L.P.
3040 Post Oak Blvd., Suite 1500
Houston, TX 77056
Telephone: (713) 623-4844
Facsimile: (713) 623-4846
Attorney for Applicant(s)

U.S. Department of Commerce, Patent and Trademark Office (PTO Form 1449 modified)					Docket No. AMAT/1931.P1/CPI/ COPPER/PJS	Serial No. 10/052,681
SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT BY APPLICANT					Applicant Xi, et al.	Confirmation No. 4083
(Use several sheets if necessary)					Filing Date January 17, 2002	Group 2814
Examiner Ginette Peralta						

U.S. Patent Documents

*Examiner Initial		Document Number	Issue Date	Applicant(s) Name	Class	Subclass	Filing Date If Appropriate
	A1	6,297,114	10/02/2001	Iwata, et al.	438	305	12/04/1998
	A2	5,792,272	08/11/1998	Van Os, et al.	118	723 IR	08/12/1997
	A3	5,759,635	06/02/1998	Logan	427	490	07/03/1996
	A4	5,565,074	10/15/1996	Qian, et al.	204	298.08	07/27/1995
	A5	5,397,962	03/14/1995	Moslehi	315	111.51	06/29/1992
	A6	4,419,202	12/06/1983	Gibson	204	192 N	12/17/1981
	A7						
	A8						
	A9						
	A10						
	A11						
	A12						
	A13						

Foreign Patent Documents

*Examiner Initial		Document Number	Date	Country	Class	Subclass	Translation	
							YES	NO
	B1						<input type="checkbox"/>	<input type="checkbox"/>
	B2						<input type="checkbox"/>	<input type="checkbox"/>
	B3						<input type="checkbox"/>	<input type="checkbox"/>
	B4						<input type="checkbox"/>	<input type="checkbox"/>
	B5						<input type="checkbox"/>	<input type="checkbox"/>

OTHER ART

*Examiner Initial		Including Author, Title, Date, Pertinent Pages, Etc.
	C1	Ghandhi, Sorab K., "VLSI Fabrication Principles, Silicon and Gallium Arsenide" Second Edition, Wiley-Interscience Publication (1994), Pages 617-620 and Page 652.
	C2	

Examiner	Date Considered
----------	-----------------

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.